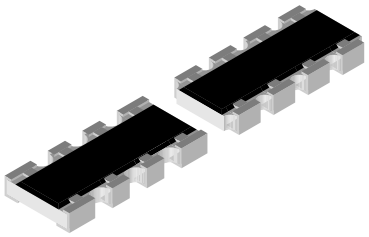
TRA06E

Vishay Dale

Thin Film, Resistor Array



FEATURES

- Flow solderable
- Automatic placement capability
- Inner electrode protection
- Wrap around termination
- Low noise, high frequency applications

STANDARD ELECTRICAL SPECIFICATIONS

MODEL	POWER RATING $P_{70°C}$ W	CIRCUIT	LIMITING ELEMENT VOLTAGE MAX. V≅	TEMPERATURE COEFFICIENT ppm/°C	TOLERANCE %	RESISTANCE RANGE Ω	E-SERIES
TRA06E	0.063	03	50	25 50 100	0.1, 0.5, 1 0.5, 1 0.5, 1	100R - 33K 10R - 91R 36K - 330K	24

- Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material
- TC temperature range: - 55°C to + 125°C
- Packaging: according to EIA 481

TECHNICAL SPECIFICATIONS

PARAMETER	UNIT	TRA06E SCHEMATIC 03
Rated Dissipation at 70°C	W	0.063
Limiting Element Voltage [1]	V≅	50
TCR Tracking Absolute	ppm/°C	± 10 ± 50 to ± 100
Category Temperature Range	°C	- 55 / + 150
Voltage Coefficient	ppm/Volt	< 0.1

[1] Rated voltage: $\sqrt{PxR}$

ORDERING INFORMATION

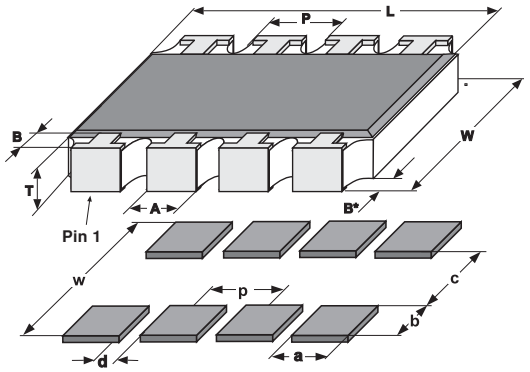
TRA06E	08	03	101	F	RT1
MODEL	TERMINAL COUNT	CIRCUIT TYPE	R-VALUE Ω	TOLERANCE ± %	PACKAGING Papertape 5000pcs
	08	03	First two digits (three for 1%) are significant. Last digit is the multiplier	B = 0.1% D = ± 0.5% F = ± 1%	

For Technical Questions, contact: ff2aresistors@vishay.com

Document Number 31054
Revision 05-Apr-04

DIMENSIONS

8-Terminal device E - Version

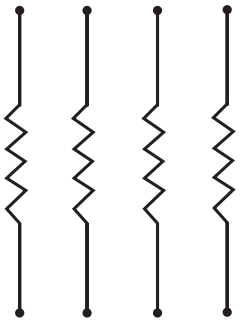


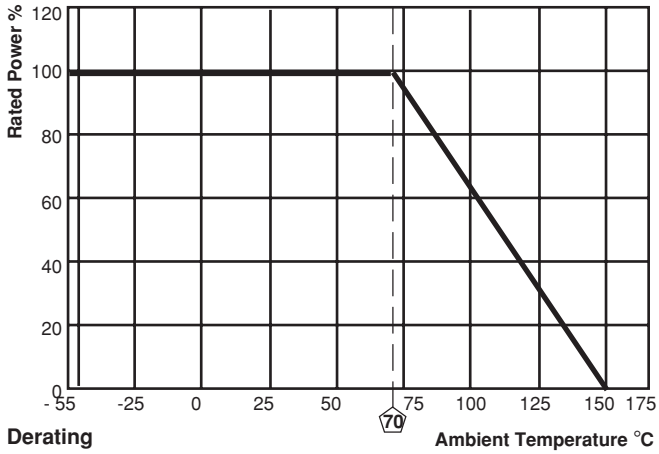
PIN	DIMENSIONS [in millimeters]					
NO:#	L	A	B	P	T	W
8	3.2 ± 0.3	0.5 ± 0.1	0.3 ± 0.2	0.8 ± 0.1	0.4 ± 0.1	1.6 ± 0.15

PIN	SOLDER PAD DIMENSIONS [in millimeters]					
NO:#	c	w	d	p	a	b
8	0.8	3.1	0.36	0.8	0.44	1.15

CIRCUIT SCHEMATIC

03 Circuit





PERFORMANCE

TEST	CONDITIONS OF TEST	TEST RESULTS
Endurance Test at 70°C per EIA 575-3.14	1000 hours at 70°C, 1.5 hours "ON", 0.5 hours "OFF"	± 3.0%
Overload per EIA 575-3.6	Short time overload	± 2.0%
Thermal Shock	per EIA 575-3.5	± 1.0%
Moisture Resistance	per EIA 575-3.10	± 1.0%
Resistance to Soldering Heat EIA 575-3.8	10 seconds at 260°C solder bath temperature	± 2.0%
High Temperature Exposure	per EIA 575-3.7	± 3.0%
Low Temperature Operations	per EIA-575-3.6	± 1.0%
Solderability & Leaching	EIA 575-3.12	95% Coverage